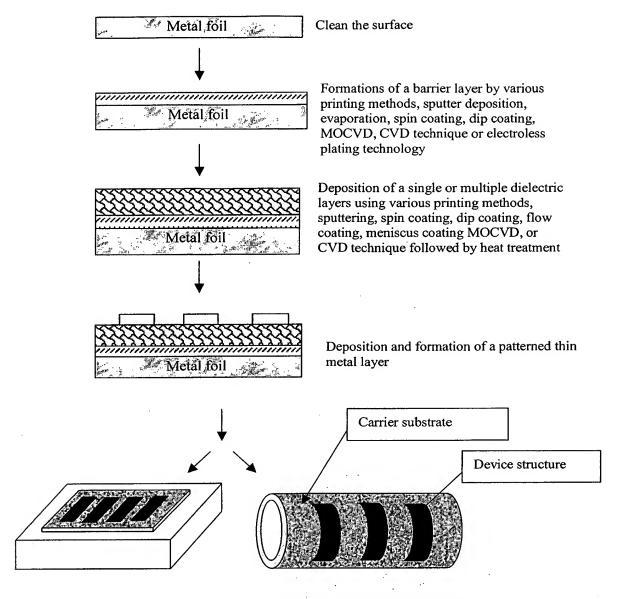
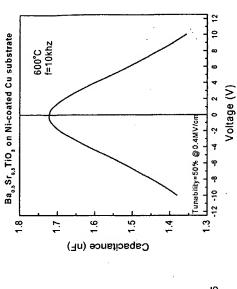


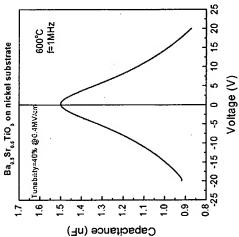
FIG. 1



Lamination of device structure on various shape carrier substrates

FIG. 2





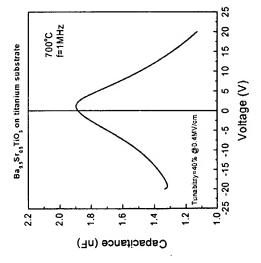


FIG. 3